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DUE TO ABRASION; 4.7 SUMMARY OF CONTACT STRESS IMPLICATIONS;
 REFERENCES; Chapter 5. Forces, Friction, and Energy; 5.1
 INTRODUCTION; 5.2 FORCES AND POWER
 5.3 FORCES: SPECIFIC ENERGY AND EFFICIENCY 5.4 EXAMPLES OF
 MATERIALS AND THEIR GRINDING CONDITIONS; 5.5 THE SIZE EFFECT;
 5.6 EFFECT OF WEAR FLAT AREA ON SPECIFIC ENERGY; 5.7 WEAR AND
 DRESSING CONDITIONS; 5.8 EFFECT OF DRESSING TOOL WEAR; 5.9 THE
 NATURE OF THE GRINDING FORCES; 5.10 FORCE RATIO AND FRICTION
 COEFFICIENT; 5.11 ADHESIVE AND ABRASIVE WHEEL WEAR; 5.12 SLIP-
 LINE FIELD SOLUTIONS; 5.13 THREE-DIMENSIONAL PYRAMID MODEL OF
 GRINDING; 5.14 LIMIT CHARTS; 5.15 PROCESS OPTIMIZATION AND
 WHEELSPEED; REFERENCES; Chapter 6. Thermal Design of Processes; 6.1
 INTRODUCTION
 6.2 EXAMPLES OF SURFACE DAMAGE 6.3 THERMAL MODELING-KEY
 DEVELOPMENTS; 6.4 RATE OF HEAT GENERATION; 6.5 TEMPERATURES
 IN GRINDING; 6.6 HEAT CONDUCTION IN THE WORKPIECE; 6.7 FLUX
 DISTRIBUTION; 6.8 PECLET NUMBER; 6.9 TEMPERATURES IN THE
 CONTACT AREA; 6.10 HEAT FLOWS IN THE CONTACT AREA AND
 PARTITIONING; 6.11 CASE STUDIES ON PROCESS VARIATIONS AND
 PROCESS DESIGN; 6.12 SUBSURFACE TEMPERATURES; 6.13 WORK-
 ABRASIVE PARTITION RATIO - R_{ws} ; APPENDIX; REFERENCES; Chapter 7.
 Molecular Dynamics for Abrasive Process Simulation; 7.1
 INTRODUCTION; 7.2 CONCEPT AND BASIC ELEMENTS OF MOLECULAR
 DYNAMICS
 7.3 REQUIREMENTS FOR MOLECULAR DYNAMICS SIMULATIONS OF
 ABRASIVE PROCESSES 7.4 APPLICATION EXAMPLES FOR MOLECULAR
 DYNAMICS SIMULATION OF ABRASIVE PROCESSES; 7.5 SUMMARY AND
 OUTLOOK; REFERENCES; Chapter 8. Fluid Delivery; 8.1 THE ROLE OF
 PROCESS FLUIDS; 8.2 OVERCOMING THE AIR BARRIER IN HIGH SPEED
 GRINDING; 8.3 NOZZLES FOR HIGH SPEED GRINDING; 8.4 ENERGY AND
 MOMENTUM REQUIREMENTS OF THE PROCESS FLUID; 8.5 USEFUL
 FLOWRATE THROUGH THE GRINDING CONTACT; 8.6 MECHANICS OF
 COOLING IN CREEP GRINDING; 8.7 SUMMARY OF CONCLUSIONS;
 REFERENCES
 Chapter 9. Electrolytic In-process Dressing (ELID) Grinding and
 Polishing

Sommario/riassunto

Recent and radically improved machining processes, from high wheel
 speeds to nanotechnology, have turned a spotlight on abrasive
 machining processes as a fertile area for further advancements. Written
 for researchers, students, engineers and technicians in manufacturing,
 this book presents a fundamental rethinking of important tribological
 elements of abrasive machining processes and their effects on process
 efficiency and product quality. Newer processes such as chemical
 mechanical polishing (CMP) and silicon wafer dicing can be better
 understood as tribological processes. Understanding the t